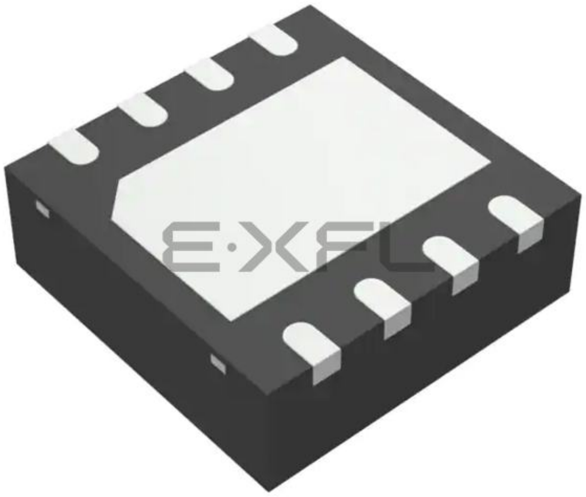

What is "Embedded - Microcontrollers"?

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN-S (6x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12f675-e-mf

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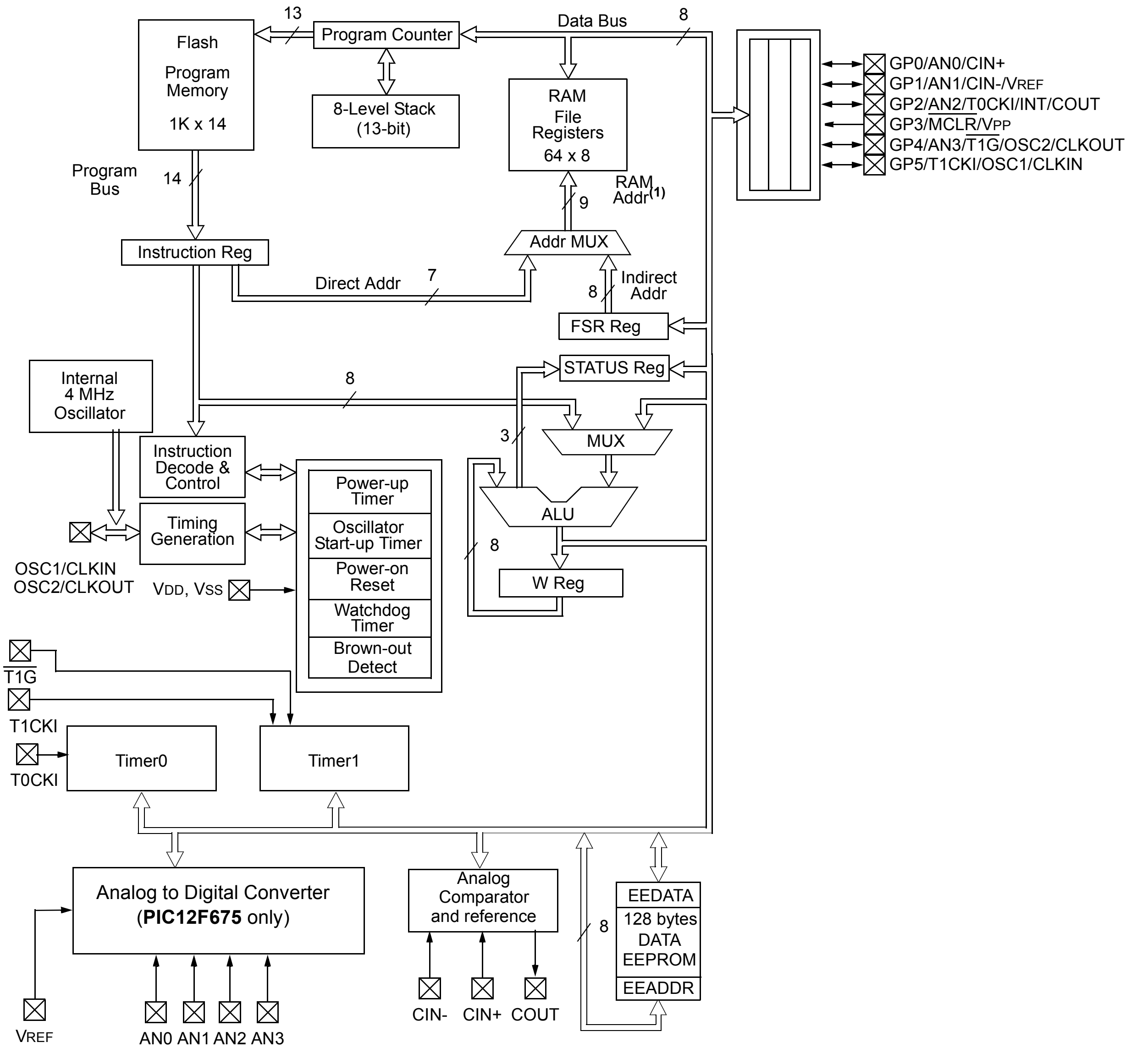
1.0 DEVICE OVERVIEW

This document contains device specific information for the PIC12F629/675. Additional information may be found in the PIC® Mid-Range Reference Manual (DS33023), which may be obtained from your local Microchip Sales Representative or downloaded from the Microchip web site. The Reference Manual should be considered a complementary document to this Data Sheet, and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

The PIC12F629 and PIC12F675 devices are covered by this Data Sheet. They are identical, except the PIC12F675 has a 10-bit A/D converter. They come in 8-pin PDIP, SOIC, MLF-S and DFN packages. Figure 1-1 shows a block diagram of the PIC12F629/675 devices. Table 1-1 shows the pinout description.

FIGURE 1-1: PIC12F629/675 BLOCK DIAGRAM



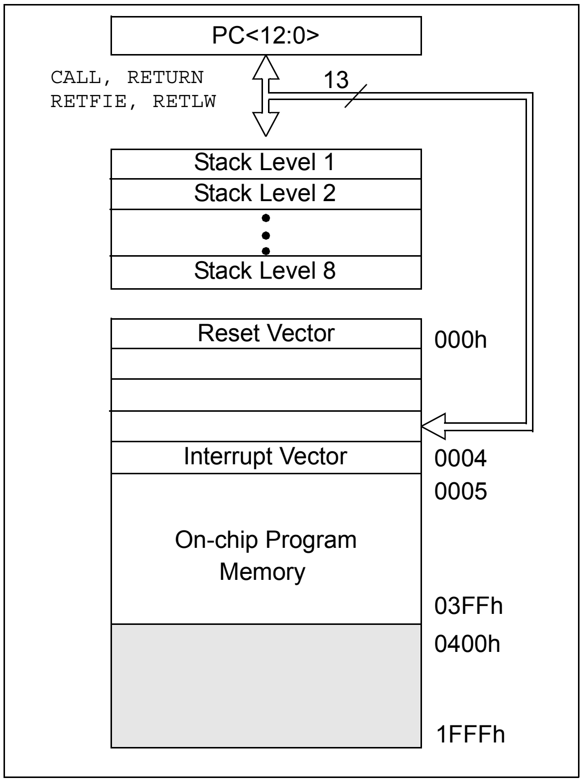
Note 1: Higher order bits are from STATUS register.

2.0 MEMORY ORGANIZATION

2.1 Program Memory Organization

The PIC12F629/675 devices have a 13-bit program counter capable of addressing an 8K x 14 program memory space. Only the first 1K x 14 (0000h-03FFh) for the PIC12F629/675 devices is physically implemented. Accessing a location above these boundaries will cause a wrap-around within the first 1K x 14 space. The Reset vector is at 0000h and the interrupt vector is at 0004h (see Figure 2-1).

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK FOR THE DSTEMP/675



2.2 Data Memory Organization

The data memory (see Figure 2-2) is partitioned into two banks, which contain the General Purpose Registers and the Special Function Registers. The Special Function Registers are located in the first 32 locations of each bank. Register locations 20h-5Fh are General Purpose Registers, implemented as static RAM and are mapped across both banks. All other RAM is unimplemented and returns '`0`' when read. RP0 (STATUS<5>) is the bank select bit.

- RP0 = `0` Bank 0 is selected
- RP0 = `1` Bank 1 is selected

Note: The IRP and RP1 bits STATUS<7:6> are reserved and should always be maintained as '`0`'s.

2.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 64 x 8 in the PIC12F629/675 devices. Each register is accessed, either directly or indirectly, through the File Select Register FSR (see **Section 2.4 "Indirect Addressing, INDF and FSR Registers"**).

2.2.2.3 INTCON Register

The INTCON register is a readable and writable register, which contains the various enable and flag bits for TMR0 register overflow, GPIO port change and external GP2/INT pin interrupts.

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 2-3: INTCON: INTERRUPT CONTROL REGISTER (ADDRESS: 0Bh OR 8Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7	**GIE:** Global Interrupt Enable bit `1` = Enables all unmasked interrupts `0` = Disables all interrupts
bit 6	**PEIE:** Peripheral Interrupt Enable bit `1` = Enables all unmasked peripheral interrupts `0` = Disables all peripheral interrupts
bit 5	**T0IE:** TMR0 Overflow Interrupt Enable bit `1` = Enables the TMR0 interrupt `0` = Disables the TMR0 interrupt
bit 4	**INTE:** GP2/INT External Interrupt Enable bit `1` = Enables the GP2/INT external interrupt `0` = Disables the GP2/INT external interrupt
bit 3	**GPIE:** Port Change Interrupt Enable bit(1) `1` = Enables the GPIO port change interrupt `0` = Disables the GPIO port change interrupt
bit 2	**T0IF:** TMR0 Overflow Interrupt Flag bit(2) `1` = TMR0 register has overflowed (must be cleared in software) `0` = TMR0 register did not overflow
bit 1	**INTF:** GP2/INT External Interrupt Flag bit `1` = The GP2/INT external interrupt occurred (must be cleared in software) `0` = The GP2/INT external interrupt did not occur
bit 0	**GPIF:** Port Change Interrupt Flag bit `1` = When at least one of the GP5:GP0 pins changed state (must be cleared in software) `0` = None of the GP5:GP0 pins have changed state

Note 1: IOC register must also be enabled to enable an interrupt-on-change.

2: T0IF bit is set when TIMER0 rolls over. TIMER0 is unchanged on Reset and should be initialized before clearing T0IF bit.

NOTES:

5.1 Timer1 Modes of Operation

Timer1 can operate in one of three modes:

- 16-bit timer with prescaler
- 16-bit synchronous counter
- 16-bit asynchronous counter

In Timer mode, Timer1 is incremented on every instruction cycle. In Counter mode, Timer1 is incremented on the rising edge of the external clock input T1CKI. In addition, the Counter mode clock can be synchronized to the microcontroller system clock or run asynchronously.

In counter and timer modules, the counter/timer clock can be gated by the $\overline{\text{T1G}}$ input.

If an external clock oscillator is needed (and the microcontroller is using the INTOSC w/o CLKOUT), Timer1 can use the LP oscillator as a clock source.

Note:	In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge.

5.2 Timer1 Interrupt

The Timer1 register pair (TMR1H:TMR1L) increments to FFFFh and rolls over to 0000h. When Timer1 rolls over, the Timer1 interrupt flag bit (PIR1<0>) is set. To enable the interrupt on rollover, you must set these bits:

- Timer1 interrupt Enable bit (PIE1<0>)
- PEIE bit (INTCON<6>)
- GIE bit (INTCON<7>).

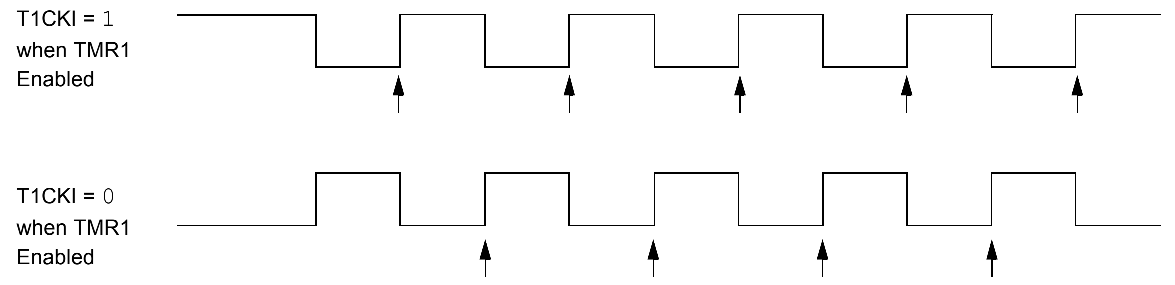
The interrupt is cleared by clearing the TMR1IF in the Interrupt Service Routine.

Note:	The TMR1H:TTMR1L register pair and the TMR1IF bit should be cleared before enabling interrupts.

5.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4, or 8 divisions of the clock input. The T1CKPS bits (T1CON<5:4>) control the prescale counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

FIGURE 5-2: TIMER1 INCREMENTING EDGE



Note 1: Arrows indicate counter increments.
2: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge of the clock.

6.0 COMPARATOR MODULE

The PIC12F629/675 devices have one analog comparator. The inputs to the comparator are multiplexed with the GP0 and GP1 pins. There is an on-chip Comparator Voltage Reference that can also be applied to an input of the comparator. In addition, GP2 can be configured as the comparator output. The Comparator Control Register (CMCON), shown in Register 6-1, contains the bits to control the comparator.

REGISTER 6-1: CMCON: COMPARATOR CONTROL REGISTER (ADDRESS: 19h)

U-0	R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	COUT	—	CINV	CIS	CM2	CM1	CM0
bit 7							bit 0

Legend:

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR
‘1’ = Bit is set
‘0’ = Bit is cleared
x = Bit is unknown

bit 7 **Unimplemented:** Read as ‘`0`’

bit 6 **COUT**: Comparator Output bit

<u>When CINV = `0`:</u>
`1` = VIN+ > VIN-
`0` = VIN+ < VIN-
<u>When CINV = `1`:</u>
`1` = VIN+ < VIN-
`0` = VIN+ > VIN-

bit 5 **Unimplemented**: Read as ‘`0`’

bit 4 **CINV**: Comparator Output Inversion bit

`1` = Output inverted
`0` = Output not inverted

bit 3 **CIS**: Comparator Input Switch bit

<u>When CM2:CM0 = `110` or `101:`</u>
`1` = VIN- connects to CIN+
`0` = VIN- connects to CIN-

bit 2-0 **CM2:CM0**: Comparator Mode bits

Figure 6-2 shows the Comparator modes and CM2:CM0 bit settings

6.5 Comparator Reference

The comparator module also allows the selection of an internally generated voltage reference for one of the comparator inputs. The internal reference signal is used for four of the eight Comparator modes. The VRCON register, Register 6-2, controls the voltage reference module shown in Figure 6-5.

6.5.1 CONFIGURING THE VOLTAGE REFERENCE

The voltage reference can output 32 distinct voltage levels, 16 in a high range and 16 in a low range.

The following equations determine the output voltages:

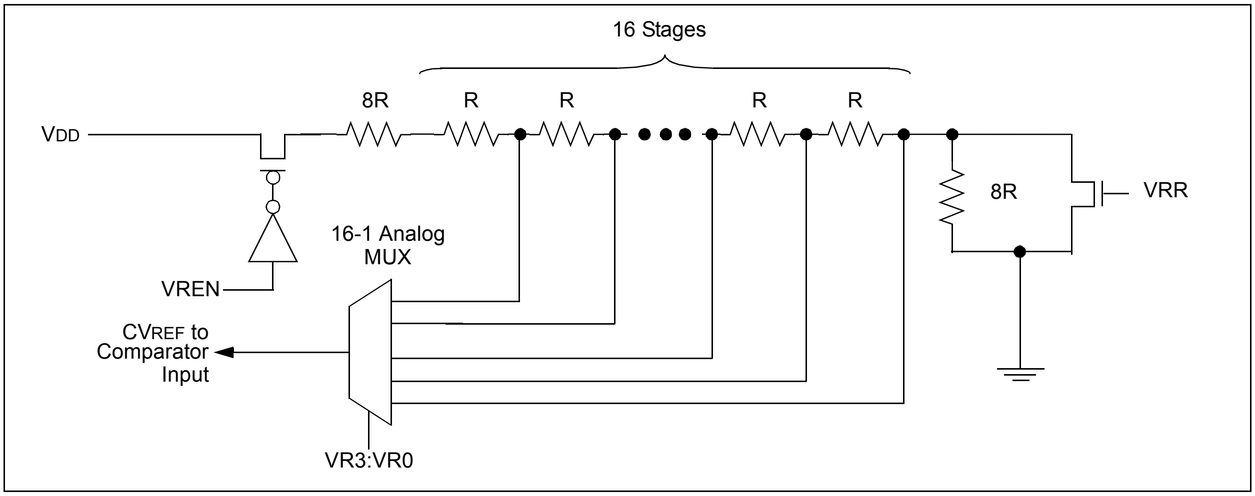
VRR = 1 (low range): CVREF = (VR3:VR0 / 24) x VDD

VRR = 0 (high range): CVREF = (VDD / 4) + (VR3:VR0 x VDD / 32)

6.5.2 VOLTAGE REFERENCE ACCURACY/ERROR

The full range of VSS to VDD cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 6-5) keep CVREF from approaching VSS or VDD. The Voltage Reference is VDD derived and therefore, the CVREF output changes with fluctuations in VDD. The tested absolute accuracy of the Comparator Voltage Reference can be found in **Section 12.0 "Electrical Specifications"**.

FIGURE 6-5: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



6.6 Comparator Response Time

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output is ensured to have a valid level. If the internal reference is changed, the maximum delay of the internal voltage reference must be considered when using the comparator outputs. Otherwise, the maximum delay of the comparators should be used (Table 12-7).

6.7 Operation During Sleep

Both the comparator and voltage reference, if enabled before entering Sleep mode, remain active during Sleep. This results in higher Sleep currents than shown in the power-down specifications. The additional current consumed by the comparator and the voltage reference is shown separately in the specifications. To minimize power consumption while in Sleep mode, turn off the comparator, CM2:CM0 = `111`, and voltage reference, VRCON<7> = `0`.

While the comparator is enabled during Sleep, an interrupt will wake-up the device. If the device wakes up from Sleep, the contents of the CMCON and VRCON registers are not affected.

6.8 Effects of a Reset

A device Reset forces the CMCON and VRCON registers to their Reset states. This forces the comparator module to be in the Comparator Reset mode, CM2:CM0 = `000` and the voltage reference to its off state. Thus, all potential inputs are analog inputs with the comparator and voltage reference disabled to consume the smallest current possible.

REGISTER 7-2: ANSEL: ANALOG SELECT REGISTER (ADDRESS: 9Fh)

U-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1
—	ADCS2	ADCS1	ADCS0	ANS3	ANS2	ANS1	ANS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **Unimplemented:** Read as ‘`0`’

bit 6-4 **ADCS<2:0>:** A/D Conversion Clock Select bits

`000` = Fosc/2
`001` = Fosc/8
`010` = Fosc/32
`x11` = FRC (clock derived from a dedicated internal oscillator = 500 kHz max)
`100` = Fosc/4
`101` = Fosc/16
`110` = Fosc/64

bit 3-0 **ANS3:ANS0:** Analog Select bits

(Between analog or digital function on pins AN<3:0>, respectively.)
`1` = Analog input; pin is assigned as analog input[(1)]
`0` = Digital I/O; pin is assigned to port or special function

Note 1: Setting a pin to an analog input automatically disables the digital input circuitry, weak pull-ups, and interrupt-on-change. The corresponding TRISIO bit must be set to Input mode in order to allow external control of the voltage on the pin.

9.1 Configuration Bits

The Configuration bits can be programmed (read as ‘0’), or left unprogrammed (read as ‘1’) to select various device configurations, as shown in Register 9.2. These bits are mapped in program memory location 2007h.

Note: Address 2007h is beyond the user program memory space. It belongs to the special configuration memory space (2000h-3FFFh), which can be accessed only during programming. See PIC12F629/675 Programming Specification for more information.

REGISTER 9-1: CONFIG: CONFIGURATION WORD (ADDRESS: 2007h)

R/P-1	R/P-1	U-0	U-0	U-0	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
BG1	BG0	—	—	—	$\overline{\text{CPD}}$	$\overline{\text{CP}}$	BODEN	MCLRE	$\overline{\text{PWRTE}}$	WDTE	F0SC2	F0SC1	F0SC0
bit 13													bit 0

Legend:
P = Programmed using ICSP™
R = Readable bit   Writable bit   U = Unimplemented bit, read as ‘0’
-n = Value at POR   1 = bit is set   0 = bit is cleared   x = bit is unknown

bit 13-12 **BG1:BG0:** Bandgap Calibration bits for BOD and POR voltage(1)
00 = Lowest bandgap voltage
11 = Highest bandgap voltage

bit 11-9 **Unimplemented**: Read as ‘0’

bit 8 **$\overline{\text{CPD}}$:** Data Code Protection bit(2)
1 = Data memory code protection is disabled
0 = Data memory code protection is enabled

bit 7 **$\overline{\text{CP}}$**: Code Protection bit(3)
1 = Program Memory code protection is disabled
0 = Program Memory code protection is enabled

bit 6 **BODEN**: Brown-out Detect Enable bit(4)
1 = BOD enabled
0 = BOD disabled

bit 5 **MCLRE**: GP3/$\overline{\text{MCLR}}$ Pin Function Select bit(5)
1 = GP3/$\overline{\text{MCLR}}$ pin function is $\overline{\text{MCLR}}$
0 = GP3/$\overline{\text{MCLR}}$ pin function is digital I/O, $\overline{\text{MCLR}}$ internally tied to VDD

bit 4 **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

bit 3 **WDTE**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 2-0 **FOSC2:FOSC0**: Oscillator Selection bits
111 = RC oscillator: CLKOUT function on GP4/OSC2/CLKOUT pin, RC on GP5/OSC1/CLKIN
110 = RC oscillator: I/O function on GP4/OSC2/CLKOUT pin, RC on GP5/OSC1/CLKIN
101 = INTOSC oscillator: CLKOUT function on GP4/OSC2/CLKOUT pin, I/O function on GP5/OSC1/CLKIN
100 = INTOSC oscillator: I/O function on GP4/OSC2/CLKOUT pin, I/O function on GP5/OSC1/CLKIN
011 = EC: I/O function on GP4/OSC2/CLKOUT pin, CLKIN on GP5/OSC1/CLKIN
010 = HS oscillator: High speed crystal/resonator on GP4/OSC2/CLKOUT and GP5/OSC1/CLKIN
001 = XT oscillator: Crystal/resonator on GP4/OSC2/CLKOUT and GP5/OSC1/CLKIN
000 = LP oscillator: Low-power crystal on GP4/OSC2/CLKOUT and GP5/OSC1/CLKIN

Note 1: The Bandgap Calibration bits are factory programmed and must be read and saved prior to erasing the device as specified in the PIC12F629/675 Programming Specification. These bits are reflected in an export of the Configuration Word. Microchip Development Tools maintain all Calibration bits to factory settings.
2: The entire data EEPROM will be erased when the code protection is turned off.
3: The entire program memory will be erased, including OSCCAL value, when the code protection is turned off.
4: Enabling Brown-out Detect does not automatically enable Power-up Timer.
5: When $\overline{\text{MCLR}}$ is asserted in INTOSC or RC mode, the internal clock oscillator is disabled.

9.3.5 BROWN-OUT DETECT (BOD)

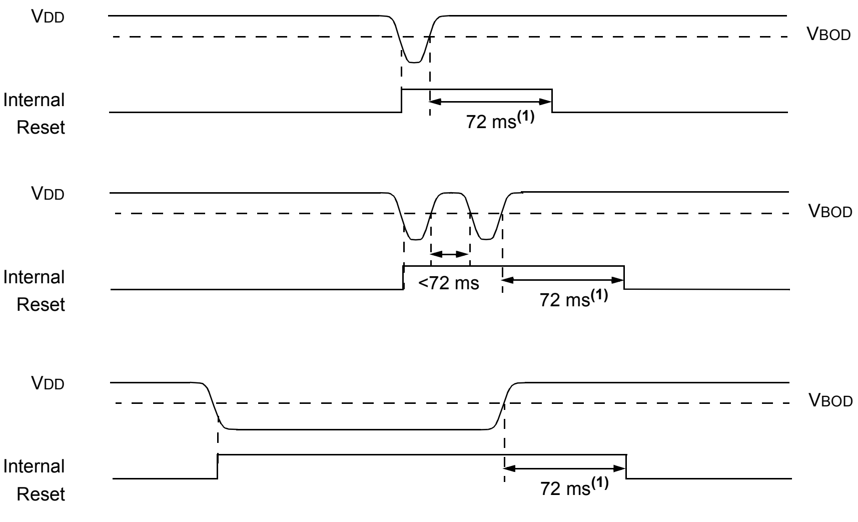
The PIC12F629/675 members have on-chip Brown-out Detect circuitry. A Configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Detect circuitry. If VDD falls below VBOD for greater than parameter (TBOD) in Table 12-4 (see **Section 12.0 "Electrical Specifications"**), the Brown-out situation will reset the device. This will occur regardless of VDD slew-rate. A Reset is not guaranteed to occur if VDD falls below VBOD for less than parameter (TBOD).

On any Reset (Power-on, Brown-out, Watchdog, etc.), the chip will remain in Reset until VDD rises above BVDD (see Figure 9-6). The Power-up Timer will now be invoked, if enabled, and will keep the chip in Reset an additional 72 ms.

Note:	A Brown-out Detect does not enable the Power-up Timer if the $\overline{\text{PWRTE}}$ bit in the Configuration Word is set.

If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Detect and the Power-up Timer will be re-initialized. Once VDD rises above BVDD, the Power-up Timer will execute a 72 ms Reset.

FIGURE 9-6: BROWN-OUT SITUATIONS



Note 1: 72 ms delay only if $\overline{\text{PWRTE}}$ bit is programmed to '0'.

9.3.6 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: first, PWRT time-out is invoked after POR has expired. Then, OST is activated. The total time-out will vary based on oscillator configuration and $\overline{\text{PWRTE}}$ bit status. For example, in EC mode with $\overline{\text{PWRTE}}$ bit erased (PWRT disabled), there will be no time-out at all. Figure 9-7, Figure 9-8 and Figure 9-9 depict time-out sequences.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 9-8). This is useful for testing purposes or to synchronize more than one PIC12F629/675 device operating in parallel.

Table 9-6 shows the Reset conditions for some special registers, while Table 9-7 shows the Reset conditions for all the registers.

9.3.7 POWER CONTROL (PCON) STATUS REGISTER

The power CONTROL/STATUS register, PCON (address 8Eh) has two bits.

Bit 0 is $\overline{\text{BOD}}$ (Brown-out). $\overline{\text{BOD}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent Resets to see if $\overline{\text{BOD}}$ = `0`, indicating that a brown-out has occurred. The $\overline{\text{BOD}}$ Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by setting $\overline{\text{BODEN}}$ bit = `0` in the Configuration Word).

Bit 1 is $\overline{\text{POR}}$ (Power-on Reset). It is a '`0`' on Power-on Reset and unaffected otherwise. The user must write a '`1`' to this bit following a Power-on Reset. On a subsequent Reset, if $\overline{\text{POR}}$ is '`0`', it will indicate that a Power-on Reset must have occurred (i.e., VDD may have gone too low).

MOVF	**Move f**
Syntax:	[*label*] MOVF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [`0`,`1`]
Operation:	(f) → (dest)
Status Affected:	Z
Description:	The contents of register f is moved to a destination dependent upon the status of d. If d = `0`, the destination is W register. If d = `1`, the destination is file register f itself. d = `1` is useful to test a file register since status flag Z is affected.
Words:	1
Cycles:	1
Example:	`MOVF  FSR, 0` After Instruction W = value in FSR register Z = `1`

MOVLW	**Move literal to W**
Syntax:	[*label*] MOVLW k
Operands:	0 ≤ k ≤ 255
Operation:	k → (W)
Status Affected:	None
Description:	The eight-bit literal ‘k’ is loaded into W register. The “don’t cares” will assemble as ‘`0`’s.
Words:	1
Cycles:	1
Example:	`MOVLW  0x5A` After Instruction W = 0x5A

MOVWF	**Move W to f**
Syntax:	[*label*] MOVWF f
Operands:	0 ≤ f ≤ 127
Operation:	(W) → (f)
Status Affected:	None
Description:	Move data from W register to register ‘f’.
Words:	1
Cycles:	1
Example:	`MOVWF  OPTION` Before Instruction OPTION = 0xFF W = 0x4F After Instruction OPTION = 0x4F W = 0x4F

NOP	**No Operation**
Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.
Words:	1
Cycles:	1
Example:	`NOP`

11.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

11.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

11.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

11.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

12.8 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

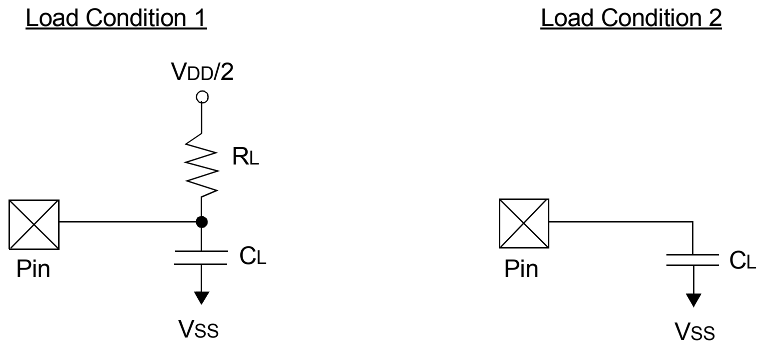
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{\text{RD}}$
cs	$\overline{\text{CS}}$	rw	$\overline{\text{RD}}$ or $\overline{\text{WR}}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{\text{SS}}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{\text{MCLR}}$	wr	$\overline{\text{WR}}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-Impedance)	V	Valid
L	Low	Z	High-Impedance

FIGURE 12-4: LOAD CONDITIONS

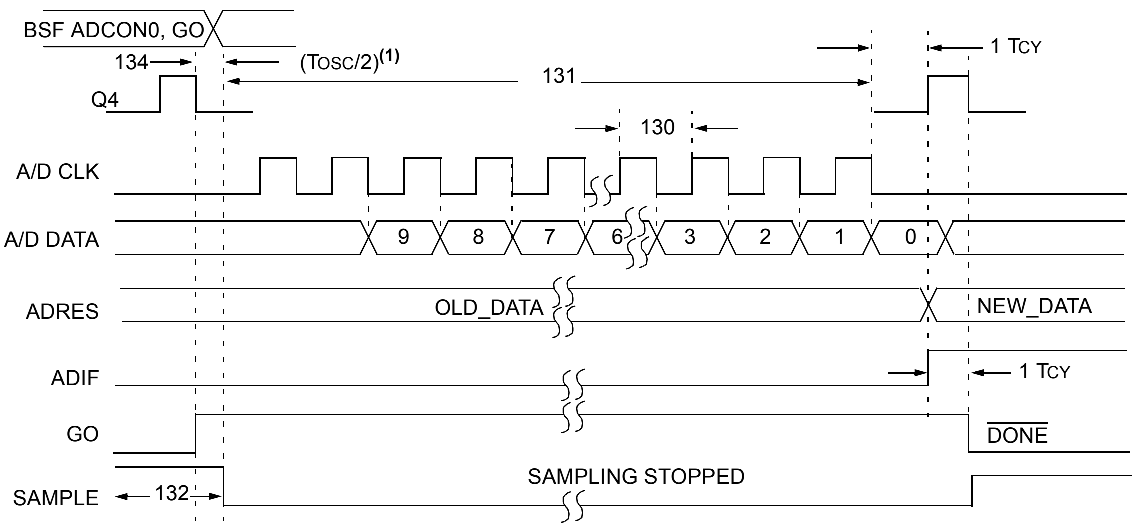


R_L = 464Ω

C_L = 50 pF for all pins

15 pF for OSC2 output

FIGURE 12-10: PIC12F675 A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the `SLEEP` instruction to be executed.

TABLE 12-9: PIC12F675 A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
130	TAD	A/D Clock Period	1.6	—	—	μs	TOSC based, VREF ≥ 3.0V
			3.0*	—	—	μs	TOSC based, VREF full range
130	TAD	A/D Internal RC Oscillator Period					ADCS<1:0> = `11` (RC mode)
			3.0*	6.0	9.0*	μs	At VDD = 2.5V
			2.0*	4.0	6.0*	μs	At VDD = 5.0V
131	TCNV	Conversion Time (not including Acquisition Time)(1)	—	11	—	TAD	Set GO bit to new data in A/D result register
132	TACQ	Acquisition Time	**(Note 2)**	11.5	—	μs	
			5*	—	—	μs	The minimum time is the amplifier settling time. This may be used if the “new” input voltage has not changed by more than 1 LSb (i.e., 4.1 mV @ 4.096V) from the last sampled voltage (as stored on CHOLD).
134	TGO	Q4 to A/D Clock Start	—	TOSC/2	—	—	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the `SLEEP` instruction to be executed.

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following TCY cycle.

2: See **Section 7.1 “A/D Configuration and Operation”** for minimum conditions.

13.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

The graphs and tables provided in this section are for **design guidance** and are **not tested**.

In some graphs or tables, the data presented are **outside specified operating range** (i.e., outside specified VDD range). This is for **information only** and devices are ensured to operate properly only within the specified range.

The data presented in this section is a **statistical summary** of data collected on units from different lots over a period of time and matrix samples. “Typical” represents the mean of the distribution at 25°C. “Max” or “min” represents (mean + 3σ) or (mean - 3σ) respectively, where σ is standard deviation, over the whole temperature range.

FIGURE 13-1: TYPICAL IPD vs. VDD OVER TEMP (-40°C TO +25°C)

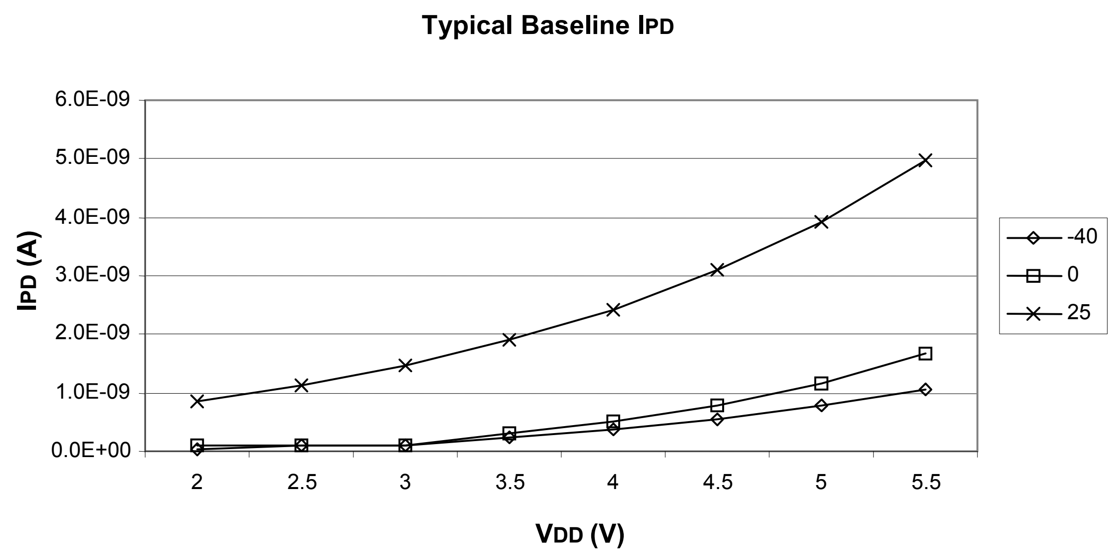


FIGURE 13-2: TYPICAL IPD vs. VDD OVER TEMP (+85°C)

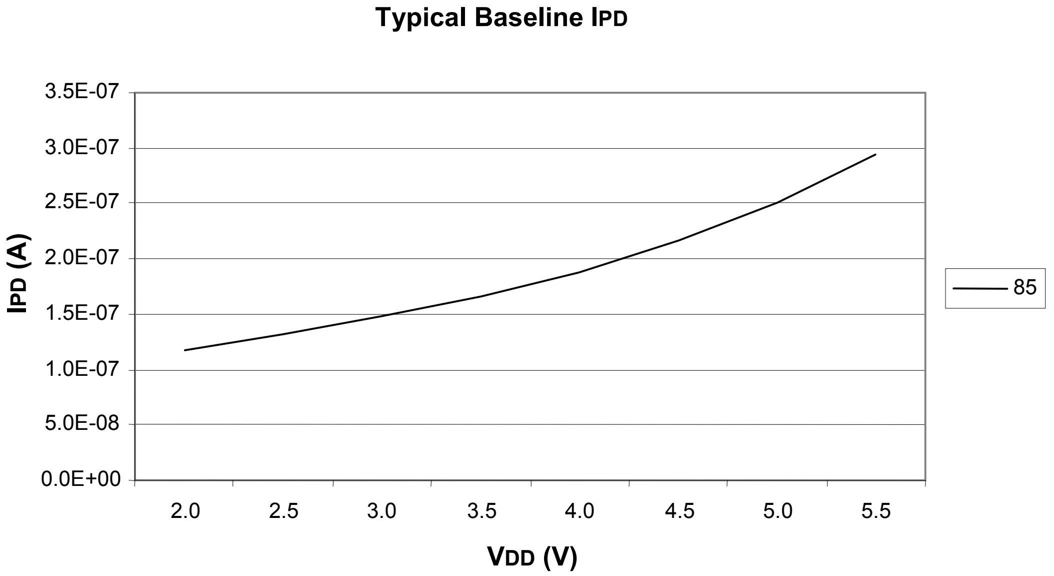


FIGURE 13-5: MAXIMUM IPD vs. VDD OVER TEMP (+85°C)

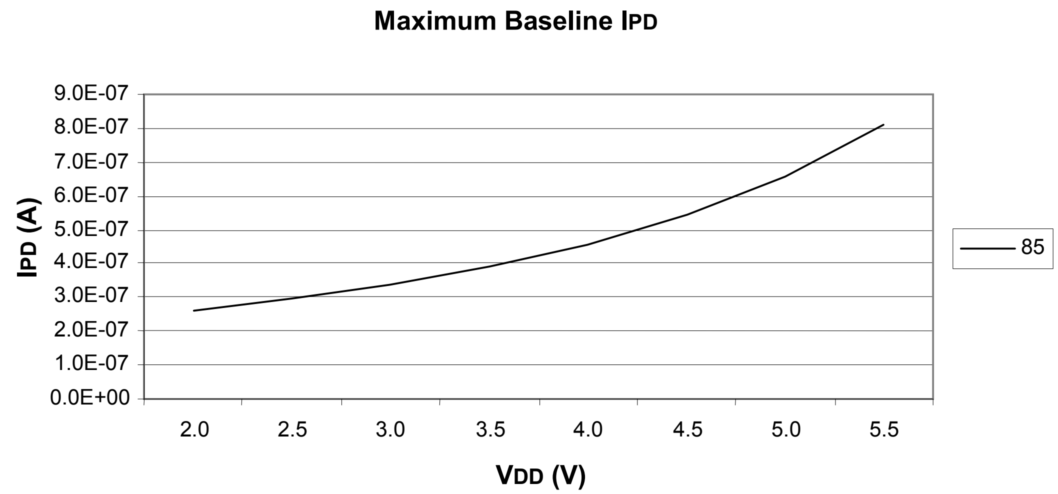
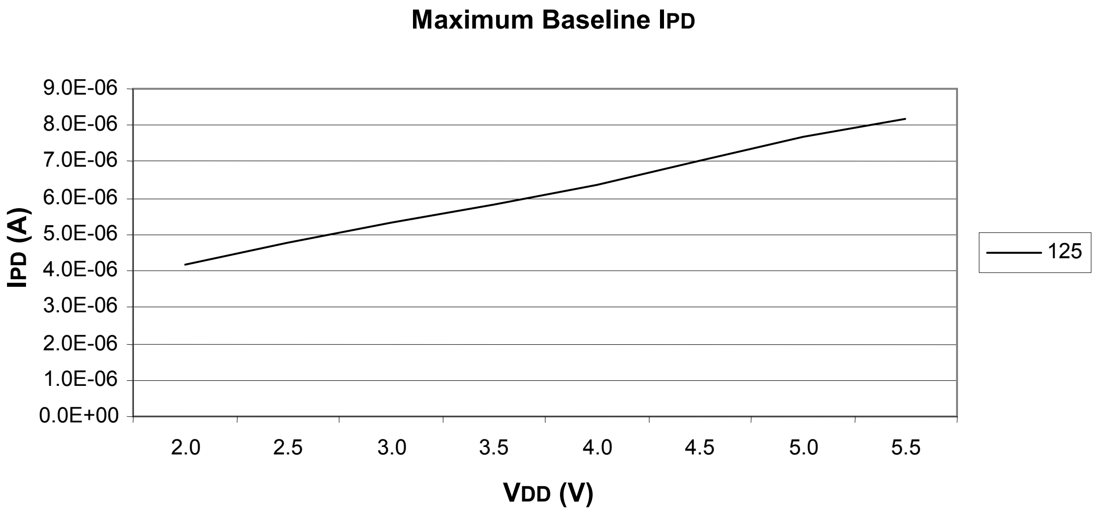
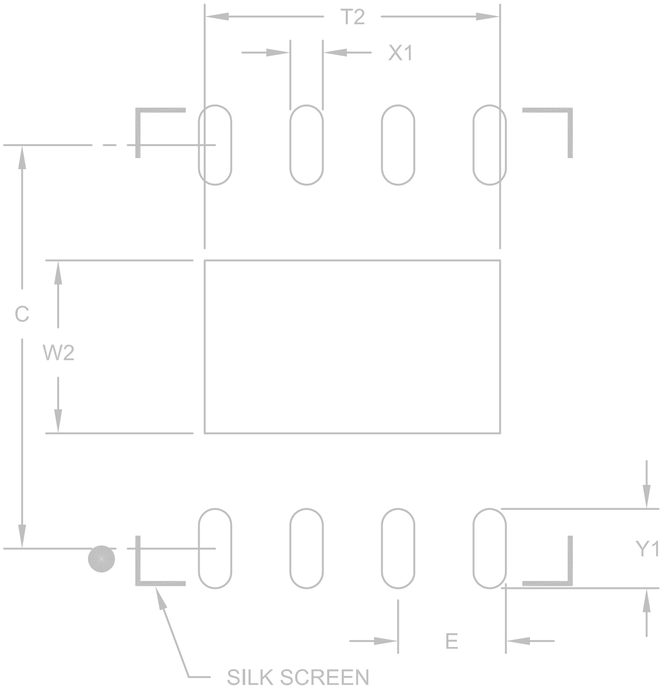


FIGURE 13-6: MAXIMUM IPD vs. VDD OVER TEMP (+125°C)

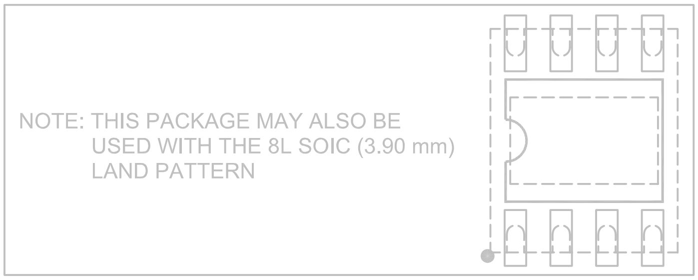


8-Lead Plastic Dual Flat, No Lead Package (MF) - 6x5 mm Body [DFN-S]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN



NOTE: THIS PACKAGE MAY ALSO BE
USED WITH THE 8L SOIC (3.90 mm)
LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Optional Center Pad Width	W2			2.40
Optional Center Pad Length	T2			4.10
Contact Pad Spacing	C		5.60	
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			1.10

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2122A

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A

This is a new data sheet.

Revision B

Added characterization graphs.

Updated specifications.

Added notes to indicate Microchip programmers maintain all Calibration bits to factory settings and the PIC12F675 ANSEL register must be initialized to configure pins as digital I/O.

Updated MLF-S package name to DFN-S.

Revision C

Revision D (01/2007)

Updated Package Drawings; Replace PICmicro with PIC; Revised Product ID example (b).

Revision E (03/2007)

Replaced Package Drawings (Rev. AM); Replaced Development Support Section.

Revision F (09/2009)

Updated Registers to new format; Added information to the “Package Marking Information” (8-Lead DFN) and “Package Details” sections (8-Lead Dual Flat, No Lead Package (MD) 4X4X0.9 mm Body (DFN)); Added Land Patterns for SOIC (SN) and DFN-S (MF) packages; Updated Register 3-2; Added MD Package to the Product identification System chapter; Other minor corrections.

Revision G (03/2010)

Updated the Instruction Set Summary section, adding pages 76 and 77.

APPENDIX B: DEVICE DIFFERENCES

The differences between the PIC12F629/675 devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Feature	PIC12F629	PIC12F675
A/D	No	Yes

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